

## CLAIMS

What is claimed is:

- 1        1.        A process for personalizing a multi-layer substrate structure comprising:  
2                supplying a generic layer having electrical features; and  
3                altering said electrical features to produce a personalized layer of said  
4        multi-layer substrate.
- 1        2.        The process in claim 1, wherein said altering comprises selectively filling  
2        vias in said generic layer with conductive material.
- 1        3.        The process in claim 1, wherein said altering comprises removing portions  
2        of electrical wiring on said generic layer.
- 1        4.        The process in claim 1, further comprising supplying a second generic  
2        layer identical to said generic layer and altering said electrical features of said  
3        second generic layer to produce a second personalized layer different than said  
4        personalized layer.
- 1        5.        The process in claim 1, wherein said altering changes said generic layer  
2        into a plurality of differently personalized layers.

1 6. The process in claim 1, wherein said generic layer includes a grid of vias  
2 useful with a plurality of differently personalized layers.

1 7. The process in claim 1, wherein said generic layer includes a pattern of  
2 wiring useful with a plurality of differently personalized layers.

1 8. The process in claim 1, wherein said altering comprises selectively filling  
2 vias in said generic layer with an insulating material.

1 9. The process in claim 1, wherein said altering comprises selectively forming  
2 insulating caps adjacent selected ones of conductive vias in said generic layer to  
3 render said selected ones of said conductive vias non-conductive.

1 10. The process in claim 9, wherein said forming of said insulating caps  
2 comprises screening a insulating paste.

1 11. The process in claim 9, wherein said forming of said insulating caps  
2 comprises placing dry insulating material over said selected ones of said  
3 conductive vias.

1 12. A process for personalizing a multi-layer substrate structure comprising:  
2 supplying a layer having generic electrical features; and  
3 altering said generic electrical features to produce a personalized layer of  
4 said multi-layer substrate.

1 13. The process in claim 12, wherein said altering comprises selectively filling  
2 vias in said layer with conductive material.

1 14. The process in claim 12, wherein said altering comprises removing  
2 portions of electrical wiring on said layer.

1 15. The process in claim 12, further comprising supplying a second layer  
2 identical to said layer and altering said generic electrical features of said second  
3 layer to produce a second personalized layer different than said personalized layer.

1 16. The process in claim 12, wherein said altering changes said layer into a  
2 plurality of differently personalized layers.

1 17. The process in claim 12, wherein said layer includes a generic grid of vias  
2 useful with a plurality of differently personalized layers.